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# DATA SHEET

## **74F30** 8-input NAND gate

Product specification

1989 Mar 03

IC15 Data Handbook

# 8-input NAND gate

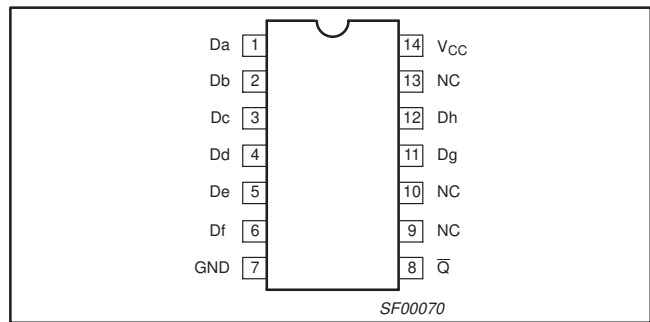
# 74F30

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F30	3.2ns	1.7mA

### ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	PKG DWG #
14-pin plastic DIP	N74F30N	SOT27-1
14-pin plastic SO	N74F30D	SOT108-1

### PIN CONFIGURATION

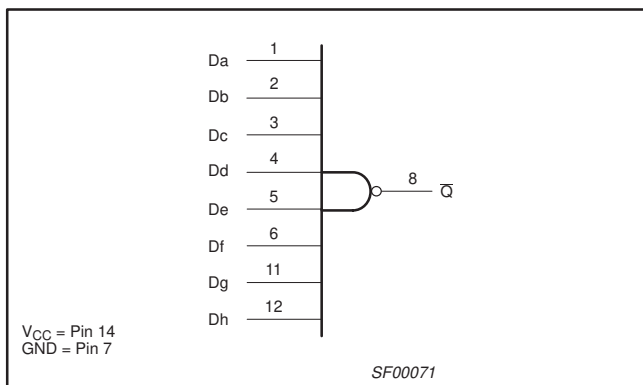


### INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dn	Data inputs	1.0/1.0	20μA/0.6mA
$\bar{Q}$	Data output	50/33	1.0mA/20mA

**NOTE:** One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

### LOGIC DIAGRAM



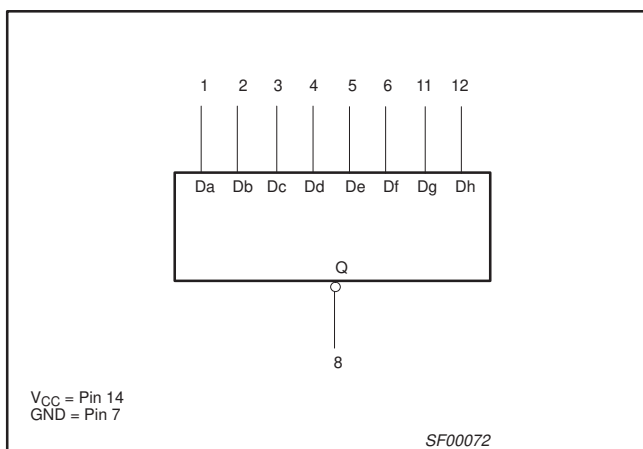
### FUNCTION TABLE

INPUTS								OUTPUT
Dna	Dnb	Dnc	Dnd	Dne	Dnf	Dng	Dnh	$\bar{Q}n$
L	X	X	X	X	X	X	X	H
X	L	X	X	X	X	X	X	H
X	X	L	X	X	X	X	X	H
X	X	X	L	X	X	X	X	H
X	X	X	X	L	X	X	X	H
X	X	X	X	X	L	X	X	H
X	X	X	X	X	X	L	X	H
X	X	X	X	X	X	X	L	H
H	H	H	H	H	H	H	H	L

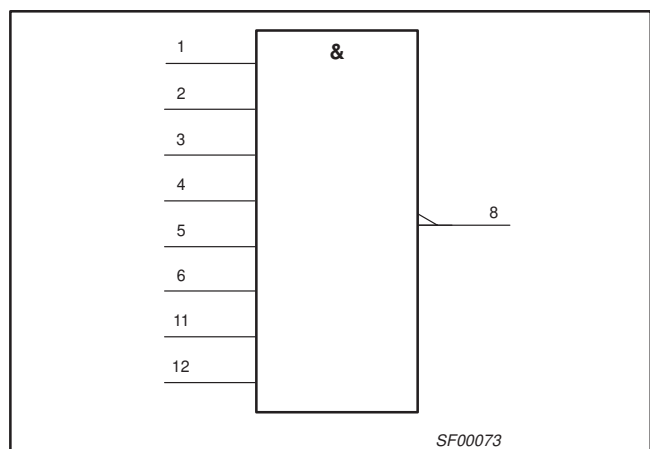
**NOTES:**

1. H = High voltage level
2. L = Low voltage level
3. X = Don't care

### LOGIC SYMBOL



### IEC/IEEE SYMBOL



# 8-input NAND gate

74F30

## ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

# 8-input NAND gate

74F30

## DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>		LIMITS			UNIT	
				MIN	TYP <sup>2</sup>	MAX		
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>	2.5			V	
		V <sub>IH</sub> = MIN, I <sub>OH</sub> = MAX	±5%V <sub>CC</sub>	2.7	3.4			
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX	±10%V <sub>CC</sub>		0.30	0.50	V	
		V <sub>IH</sub> = MIN, I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50		
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = I <sub>IK</sub>			-0.73	-1.2	V	
I <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0V				100	μA	
I <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7V				20	μA	
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5V				-0.6	mA	
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>	V <sub>CC</sub> = MAX		-60		-150	mA	
I <sub>CC</sub>	Supply current (total)	I <sub>CCH</sub>	V <sub>CC</sub> = MAX	V <sub>IN</sub> = GND		0.6	1.5	mA
		I <sub>CCL</sub>		V <sub>IN</sub> = 4.5V		2.8	4.0	

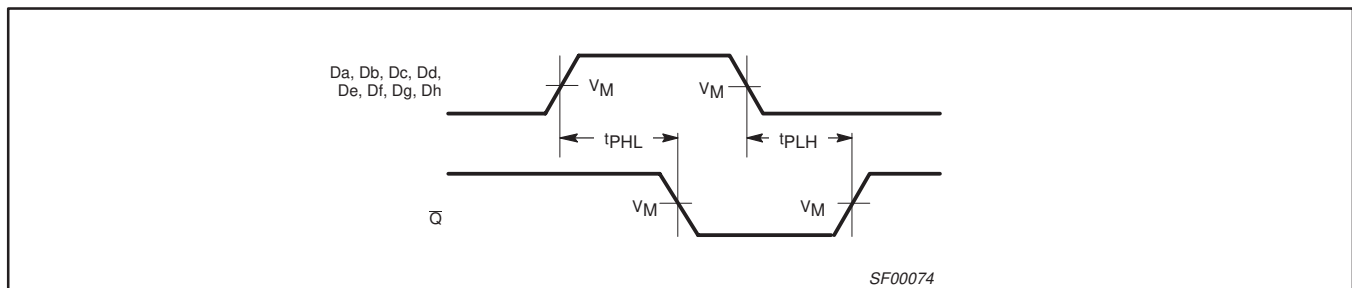
**NOTES:**

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
3. Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

## AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Da, Db, Dc, Dd, De, Df, Dg, Dh to $\bar{Q}$	Waveform 1	1.5 1.0	3.5 3.0	5.0 4.5	1.5 1.0	5.5 5.0	ns

## AC WAVEFORMS



Waveform 1. Propagation Delay for Inverting Outputs

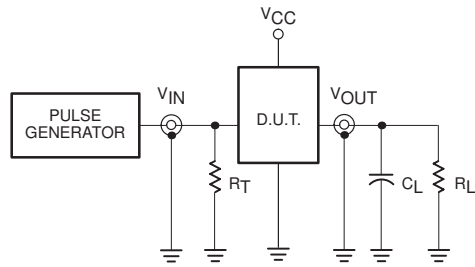
**NOTE:**

For all waveforms, V<sub>M</sub> = 1.5V.

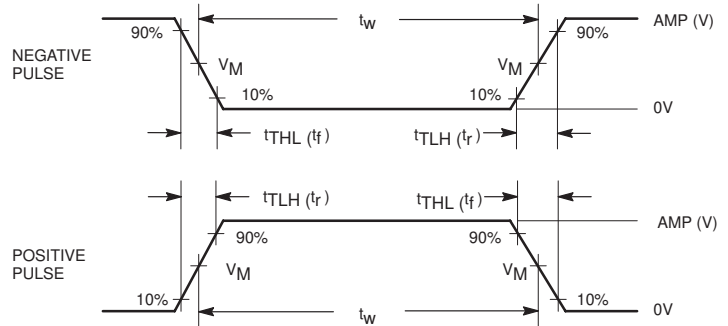
# 8-input NAND gate

# 74F30

## TEST CIRCUIT AND WAVEFORMS



Test Circuit for Totem-Pole Outputs



Input Pulse Definition

**DEFINITIONS:**

- $R_L$  = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

family	INPUT PULSE REQUIREMENTS					
	amplitude	$V_M$	rep. rate	$t_w$	$t_{TLH}$	$t_{THL}$
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

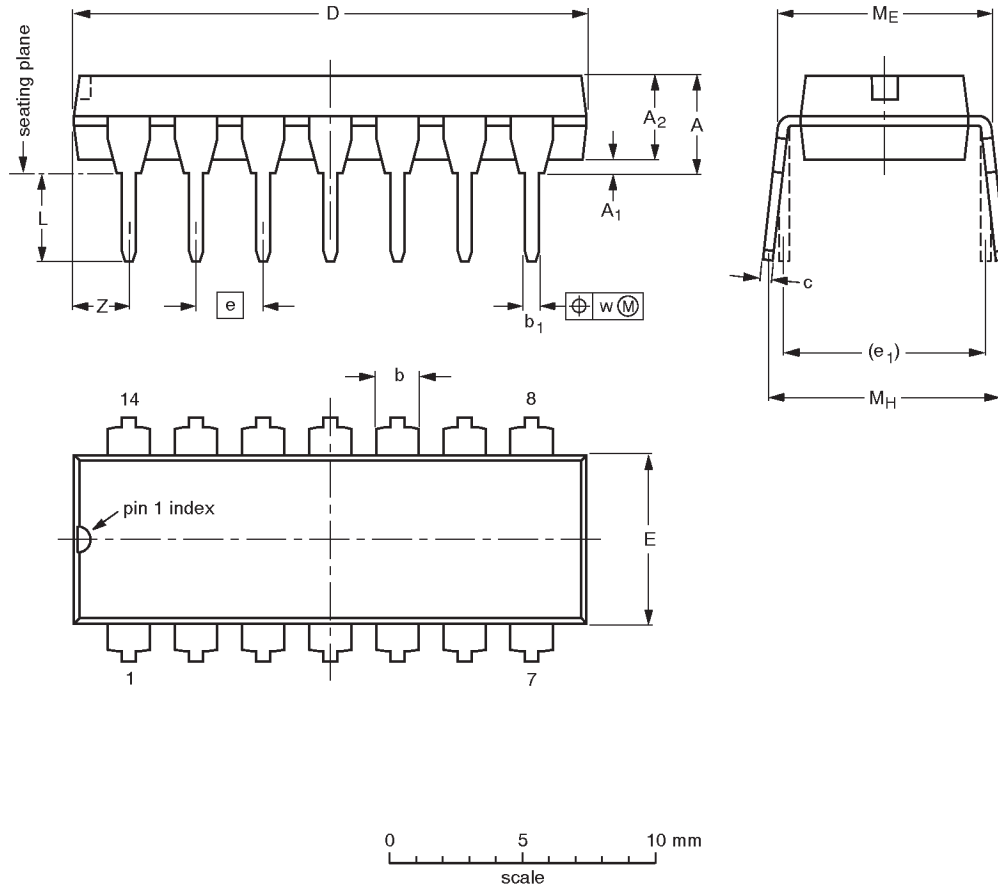
SF00006

# 8-input NAND gate

# 74F30

**DIP14: plastic dual in-line package; 14 leads (300 mil)**

**SOT27-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

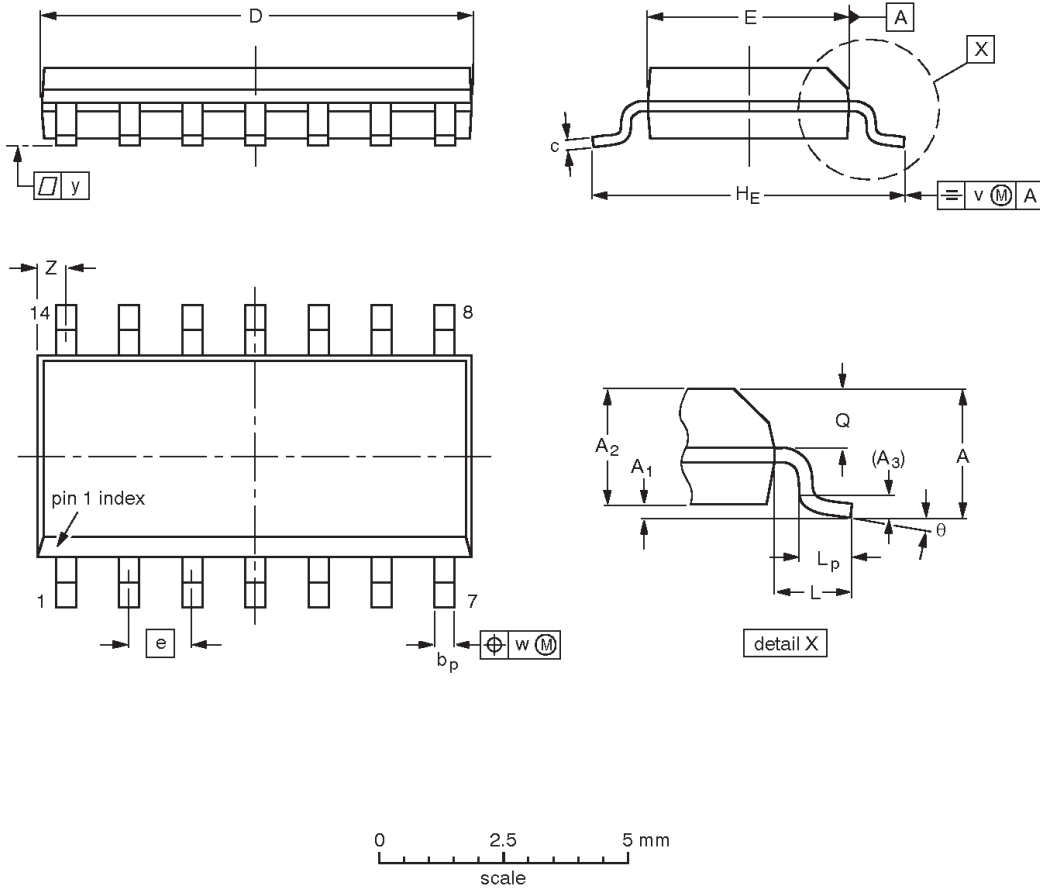
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11

# 8-input NAND gate

74F30

**SO14: plastic small outline package; 14 leads; body width 3.9 mm**

**SOT108-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	$\theta$
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT108-1	076E06S	MS-012AB			95-01-29 97-05-22



## 8-input NAND gate

74F30

**Data sheet status**

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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